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Front Matter: Volume 10085

, "Front Matter: Volume 10085," Proc. SPIE 10085, Components and Packaging for Laser Systems III, 1008501 (20 March 2017); doi: 10.1117/12.2276037

SPIE.

Event: SPIE LASE, 2017, San Francisco, California, United States

PROCEEDINGS OF SPIE

Components and Packaging for Laser Systems III

Alexei L. Glebov
Paul O. Leisher
Editors

31 January–2 February 2017
San Francisco, California, United States

Sponsored and Published by
SPIE

Volume 10085

Proceedings of SPIE 0277-786X, V. 10085

SPIE is an international society advancing an interdisciplinary approach to the science and application of light.

Components and Packaging for Laser Systems III, edited by Alexei L. Glebov, Paul O. Leisher, Proc. of SPIE
Vol. 10085, 1008501 · © 2017 SPIE · CCC code: 0277-786X/17/\$18 · doi: 10.1117/12.2276037

Proc. of SPIE Vol. 10085 1008501-1

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Author(s), "Title of Paper," in *Components and Packaging for Laser Systems III*, edited by Alexei L. Glebov, Paul O. Leisher, Proceedings of SPIE Vol. 10085 (SPIE, Bellingham, WA, 2017) Seven-digit Article CID Number.

ISSN: 0277-786X
ISSN: 1996-756X (electronic)

ISBN: 9781510606111
ISBN: 9781510606128 (electronic)

Published by

SPIE

P.O. Box 10, Bellingham, Washington 98227-0010 USA
Telephone +1 360 676 3290 (Pacific Time) · Fax +1 360 647 1445
SPIE.org

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